

General Description

The MY20N06A is the high cell density trenched N-CH MOSFETs, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications.

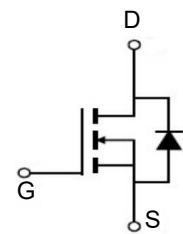
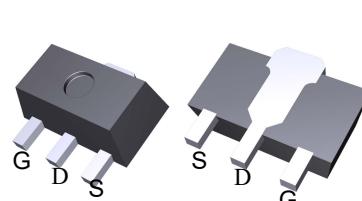


Features

V_{DSS}	60	V
I_D	20	A
$R_{DS(ON)}(\text{at } V_{GS}=10\text{V})$	<35	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=4.5\text{V})$	<40	$\text{m}\Omega$

Application

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY20N06A	SOT-89	MY20N06A	1000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage	± 30	V
I_D	$T_C = 25^\circ\text{C}$	20	A
		14	A
I_{DM}	Pulsed Drain Current ^{note1}	80	A
EAS	Single Pulsed Avalanche Energy ^{note2}	72	nd
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	45.7	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	50	$^\circ\text{C} / \text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$

Electrical Characteristics at $T_J=25\text{ }^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\text{pA}$	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	pA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\text{pA}$	1.2	1.6	2.5	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$	-	24	35	mQ
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D = 8\text{A}$		30	40	
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=10\text{A}$	11	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $\text{F}=1.0\text{MHz}$	-	973.2	-	PF
Output Capacitance	C_{oss}		-	61.2	-	PF
Reverse Transfer Capacitance	C_{rss}		-	58.8	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=30\text{V}, \text{R}_{\text{L}}=3\text{Q}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{G}}=3\text{Q}$	-	7	-	nS
Turn-on Rise Time	t_{r}		-	20	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	16	-	nS
Turn-Off Fall Time	t_{f}		-	23	-	nS
Total Gate Charge	Q_{g}	$\text{V}_{\text{DS}}=30\text{V}, \text{I}_D=10\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	25	-	nC
Gate-Source Charge	Q_{gs}		-	4.5	-	nC
Gate-Drain Charge	Q_{gd}		-	6.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=10\text{A}$	-		1.2	V
Diode Forward Current ^(Note 2)	I_{s}		-	-	20	A
Reverse Recovery Time	t_{rr}	$\text{T}_{\text{J}} = 25\text{ }^{\circ}\text{C}, \text{IF} = 10\text{A}$ $\frac{\text{di}/\text{dt}}{\text{Q}_{\text{rr}}} = 100\text{A}/\text{ps}$ ^(Note 3)	-	29	-	nS
Reverse Recovery Charge	Q_{rr}		-	49	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\text{ps}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $\text{T}_{\text{J}}=25\text{ }^{\circ}\text{C}$, $\text{V}_{\text{DD}}=30\text{V}$, $\text{V}_{\text{G}}=10\text{V}$, $\text{L}=0.5\text{mH}$, $\text{R}_{\text{G}}=25\text{Q}$

Typical Characteristics

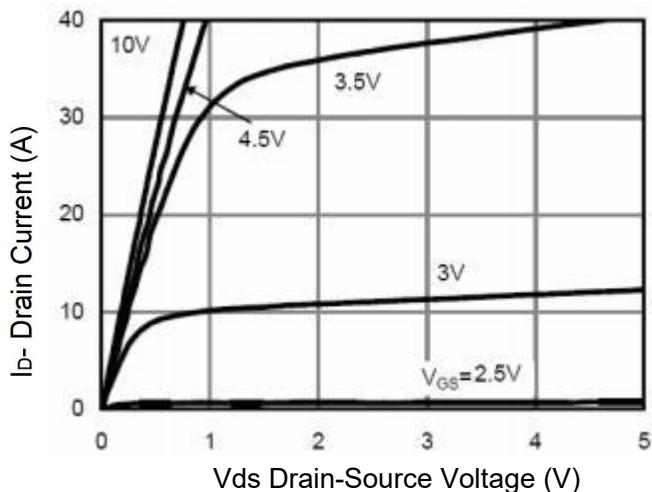


Figure 1 Output Characteristics

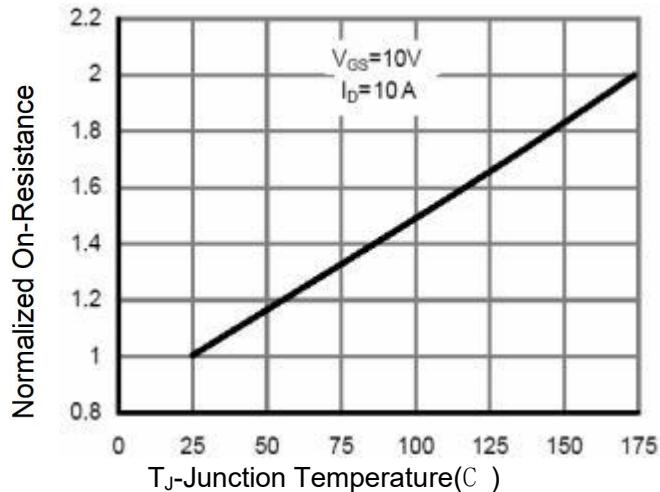
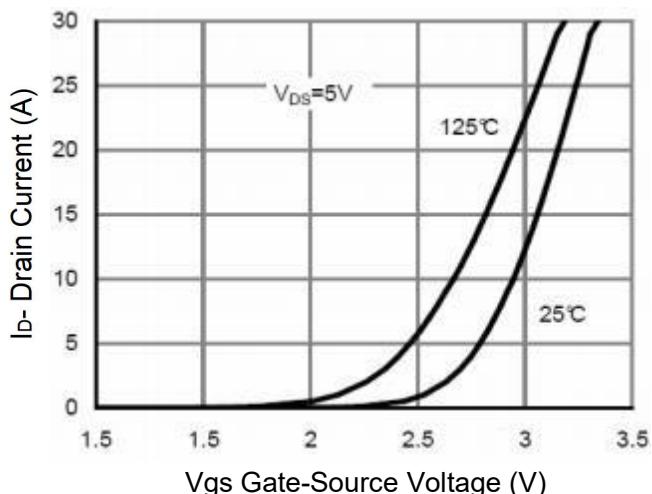
Figure 4 $R_{DS(on)}$ -Junction Temperature

Figure 2 Transfer Characteristics

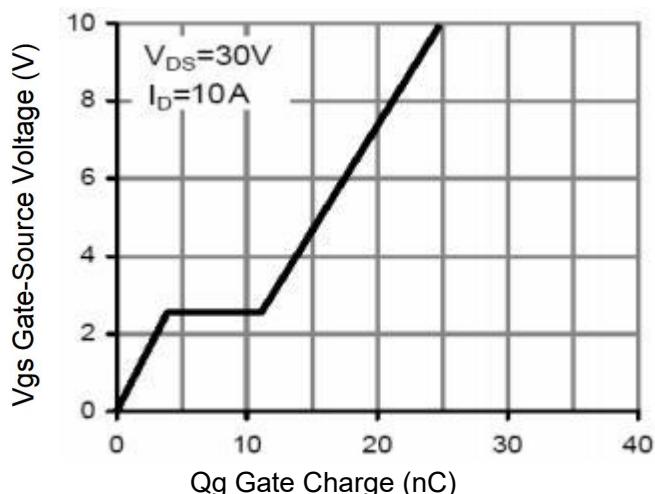


Figure 5 Gate Charge

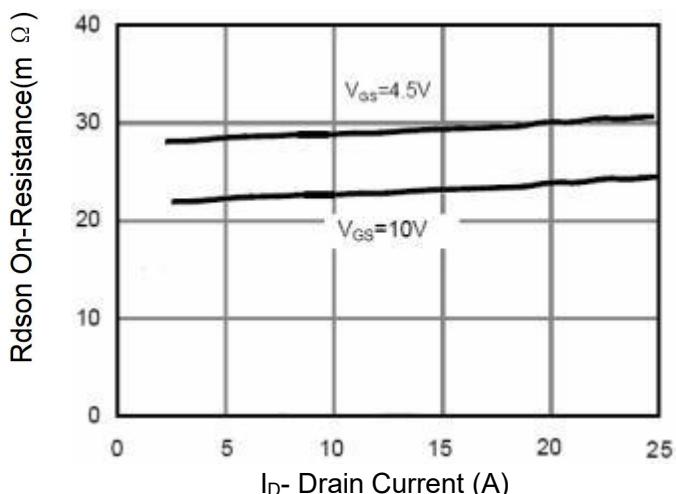
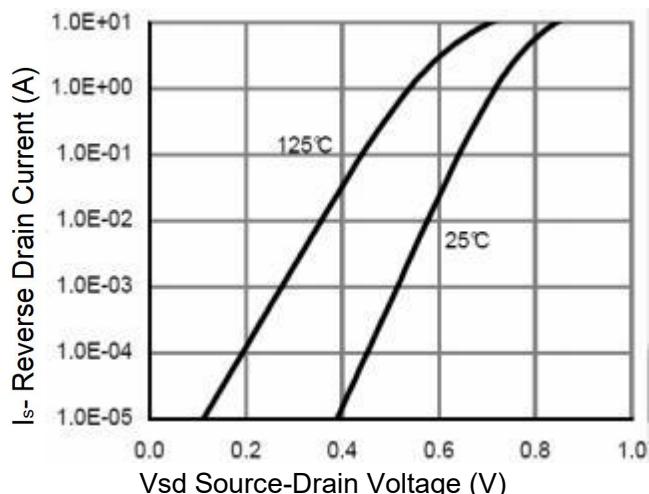
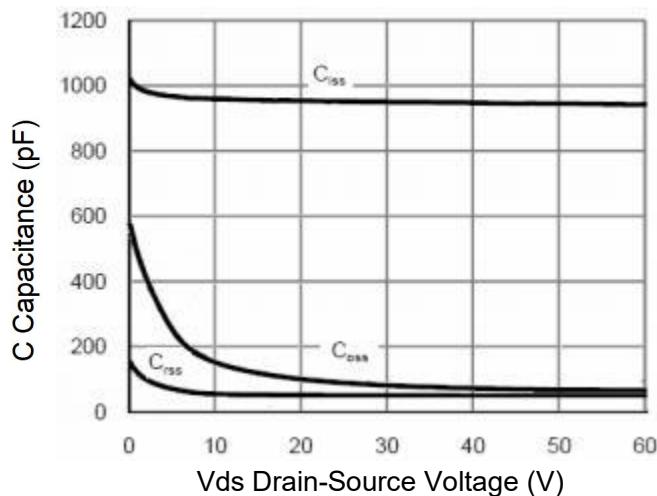
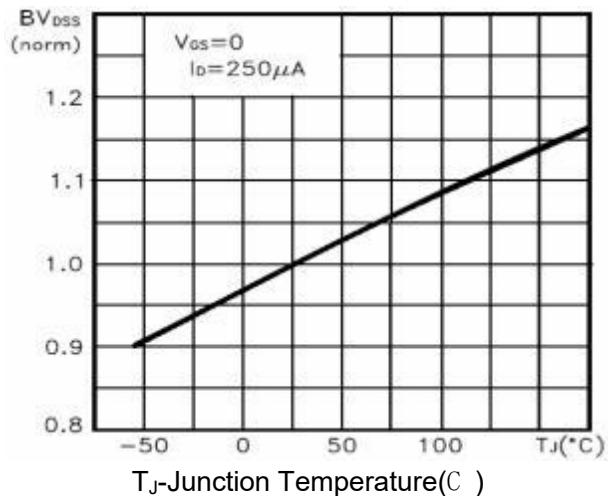
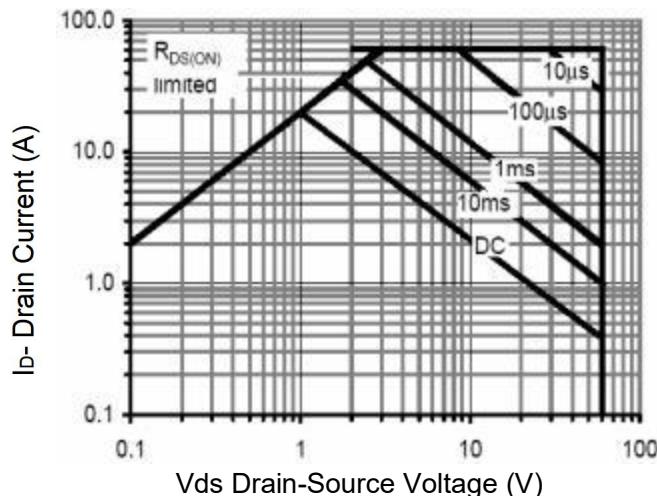
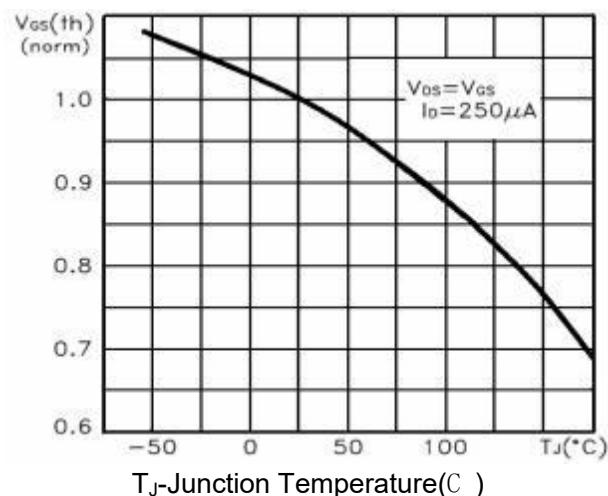
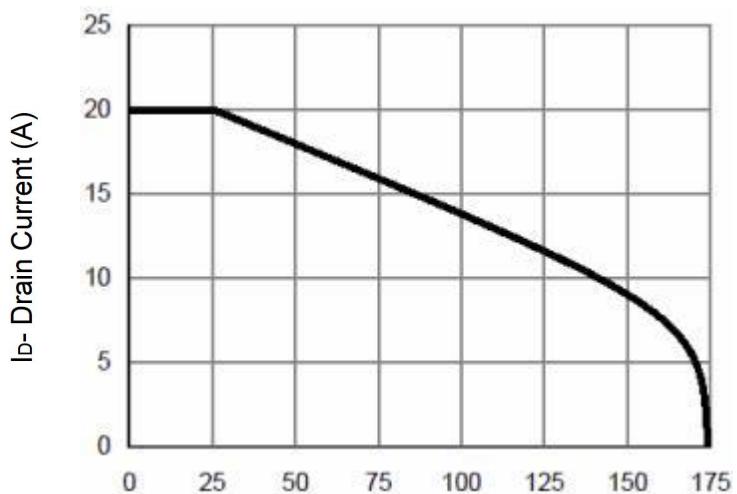
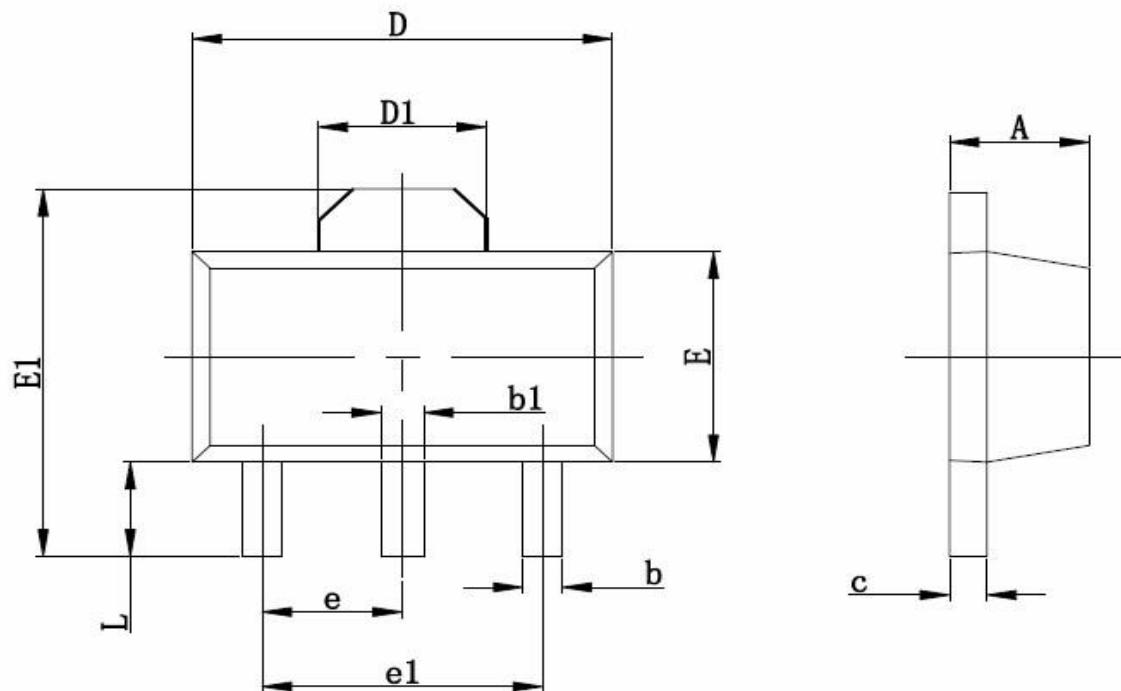
Figure 3 $R_{DS(on)}$ - Drain Current

Figure 6 Source- Drain Diode Forward

**Figure 7 Capacitance vs Vds****Figure 9 BV_{DSS} vs Junction Temperature****Figure 8 Safe Operation Area****Figure 10 $V_{GS(th)}$ vs Junction Temperature****Figure 11 Current De-rating**

Package Mechanical Data SOT-89



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.350	0.520	0.013	0.197
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF		0.061 REF	
E	2.350	2.550	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP		0.060 TYP	
e1	3.000 TYP		0.118 TYP	
L	0.900	1.100	0.035	0.047